

**Amendments to the Abstract:**

**Please replace the previous Abstract with the following redlined Abstract:**

~~It is an object of the present invention is to provide a method for manufacturing a multi-layered ceramic electronic component which can reliably prevent a multi-layered unit including a ceramic green sheet and an electrode layer from being damaged and efficiently laminate a desired number of the multi-layered units, thereby manufacturing the multi-layered ceramic electronic component.~~

The A method for manufacturing a multi-layered ceramic electronic component ~~according to the present invention includes a step of~~includes positioning a multi-layered unit including a release layer, an electrode layer and a ceramic green sheet formed on a support sheet in such a manner that the surface of the multi-layered unit is located on a base substrate and a step of pressing the multi-layered unit toward the base substrate, thereby laminating the multi-layered unit on the base substrate, and employs as the base substrate a base substrate having such surface roughness as to include per  $0.01 \text{ mm}^2$  thereof not more than one protrusion that can penetrate the ceramic green sheet of the multi-layered unit laminated on the base substrate to half or more the thickness of the ceramic green sheet and include per  $100 \text{ mm}^2$  thereof not more than one protrusion that can completely penetrate the ceramic green sheet.